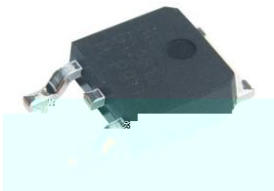
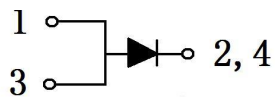


TO-252

Schottky Diode in a TO-252 Plastic Package.

High Forward Surge Capability, Ultra Low Forward Voltage Drop, Excellent High Temperature Stability.

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.



PIN1 Anode

PIN 2,4 Cathode

PIN 3 Anode

See Marking Instructions.

| Parameter                                                                              | Symbol                            | Rating   | Unit |
|----------------------------------------------------------------------------------------|-----------------------------------|----------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage | $V_{RM}$<br>$V_{RSM}$<br>$V_{DC}$ | 100      | V    |
| RMS Reverse Voltage                                                                    | $V_{RMS}$                         | 70       | V    |
| Average forward rectified current                                                      | $I_{F(AV)}$                       | 1×10     | A    |
| Non Repetitive Peak Surge Current                                                      | $I_{FSM}$                         | 200      | A    |
| Thermal Resistance Junction to Case                                                    | $R_{\theta Jc}$                   | 2.0      | /W   |
| Junction and Storage Temperature Range                                                 | $T_j$ $T_{stg}$                   | -55 +150 |      |

| Parameter                     | Symbol          | Test Conditions             | Min | Typ  | Max  | Unit    |
|-------------------------------|-----------------|-----------------------------|-----|------|------|---------|
| Reverse Voltage               | $V_{(BR)R}$     | $I_R=1mA(T_a=25^\circ C)$   | 100 |      |      | V       |
| Forward Voltage               | $V_F$           | $I_F=2A(T_a=25^\circ C)$    |     | 0.41 | 0.45 | V       |
|                               |                 | $I_F=10A(T_a=25^\circ C)$   |     | 0.58 | 0.65 | V       |
|                               |                 | $I_F=2A(T_a=125^\circ C)$   |     | 0.31 | 0.40 | V       |
|                               |                 | $I_F=10A(T_a=125^\circ C)$  |     | 0.55 | 0.65 | V       |
| Instantaneous Reverse Current | $I_R$<br>Note 1 | $V_R=100V(T_a=25^\circ C)$  |     |      | 150  | $\mu A$ |
|                               |                 | $V_R=100V(T_a=125^\circ C)$ |     |      | 25   | mA      |

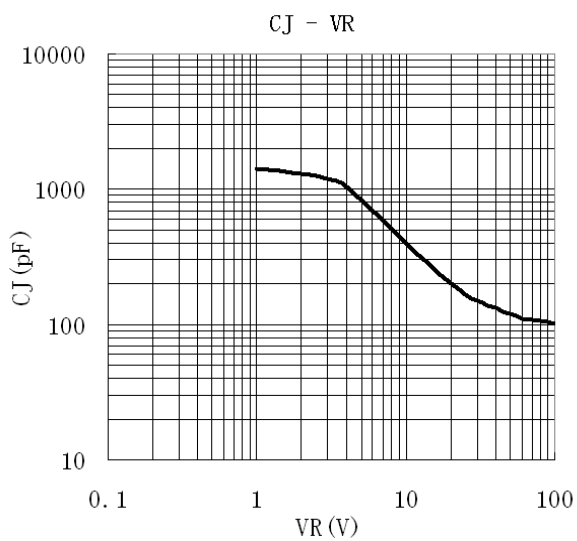
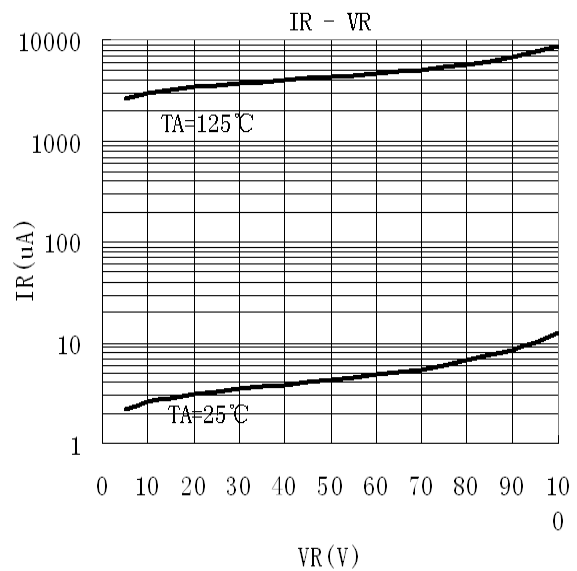
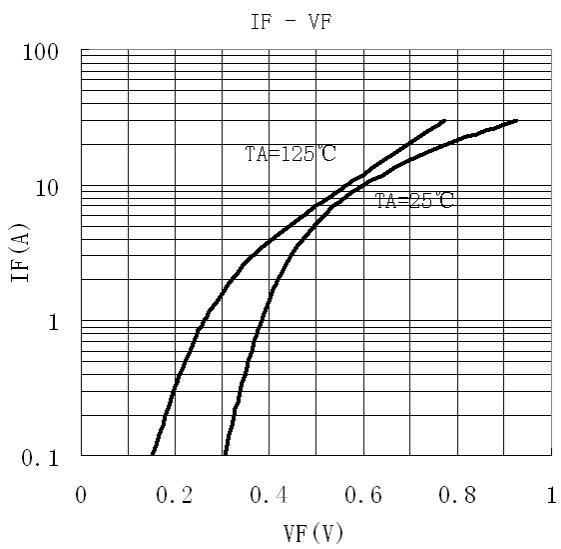
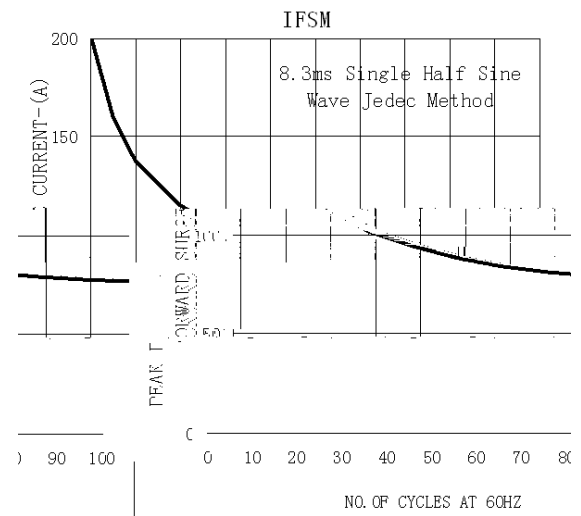
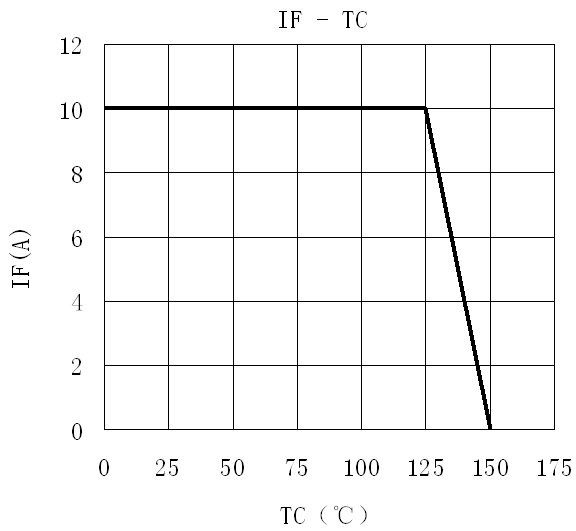
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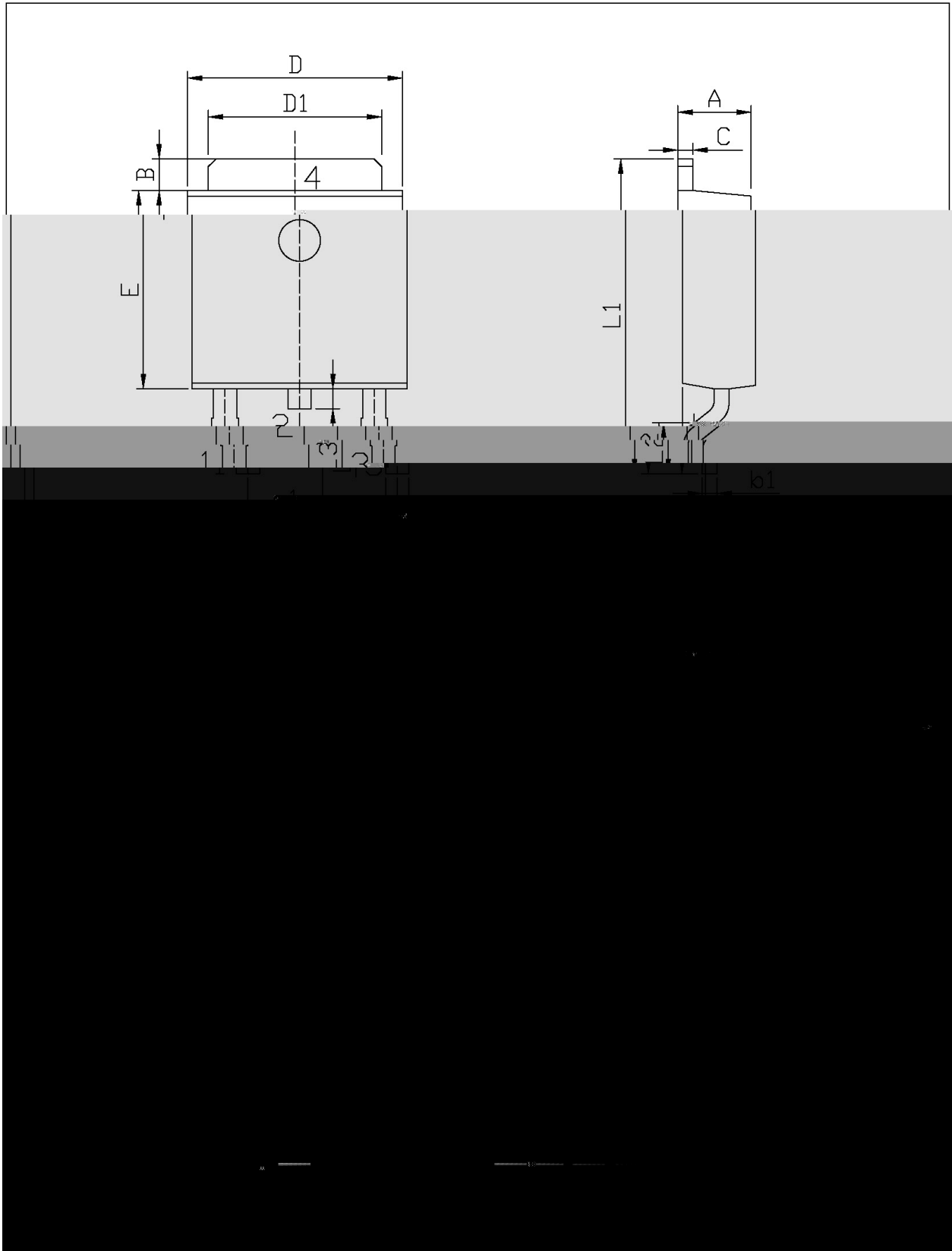
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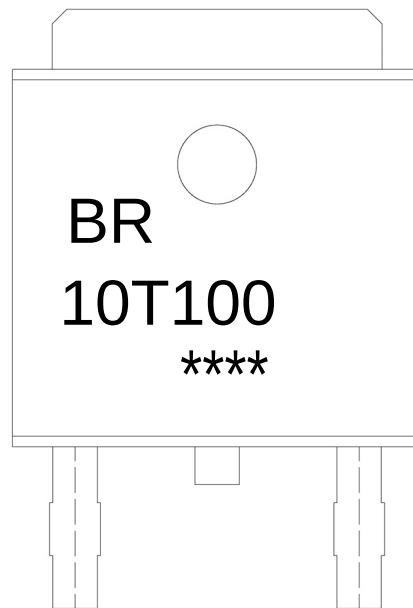
Short duration pulse test used to minimize self-heating effect.

2.

Unless otherwise noted, values for the parameters of a single chip







BR

10T100

\*\*\*\*

Note:

BR:

10T100

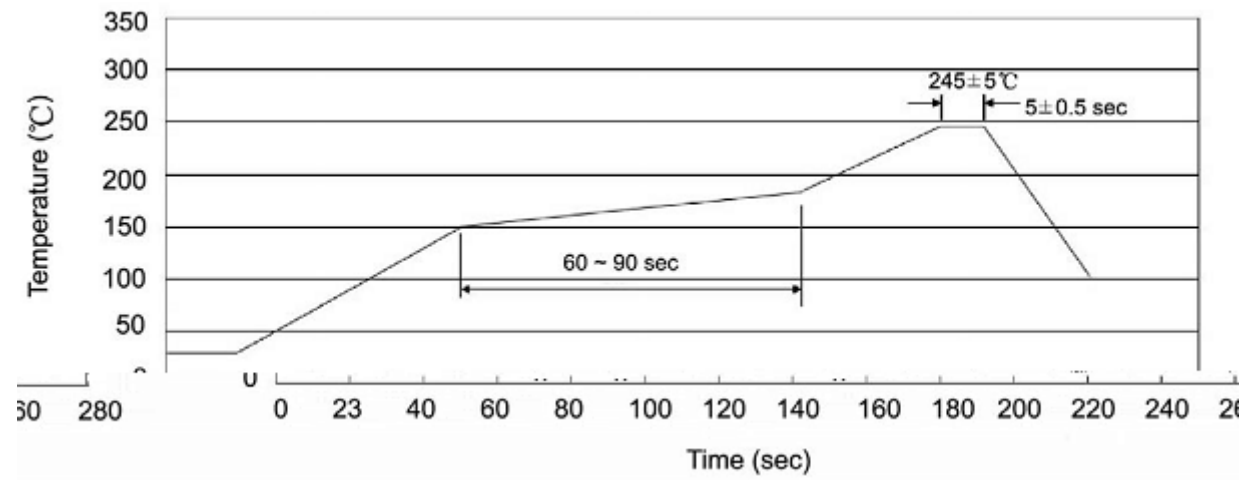
\*\*\*\*:

Company Code

Product Type Code.

Lot No. Code, code change with Lot No.

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |    |           |                                         |
|---|-------|-----|----|-----------|-----------------------------------------|
| 1 | 25    | 150 | 60 | 90sec;    | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5 |     |    | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       | 2   | 10 | /sec.     | 3. Cooling Speed: 2~10 /sec.            |